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(12) **United States Design Patent**
Shinkai

(10) **Patent No.:** **US D693,318 S**
(45) **Date of Patent:** **** Nov. 12, 2013**

(54) **SEMICONDUCTOR MODULE FOR POWER CONVERSION**

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Osaka-shi (JP)

(**) Term: **14 Years**

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(30) **Foreign Application Priority Data**

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(51) **LOC (9) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/182**

(58) **Field of Classification Search**

USPC D13/110, 182; 361/748, 760, 783, 787,
361/813, 774, 784, 785, 713, 728, 736,
361/752; 257/787, 668, 678, 690

See application file for complete search history.

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Primary Examiner — Elizabeth J Oswecki

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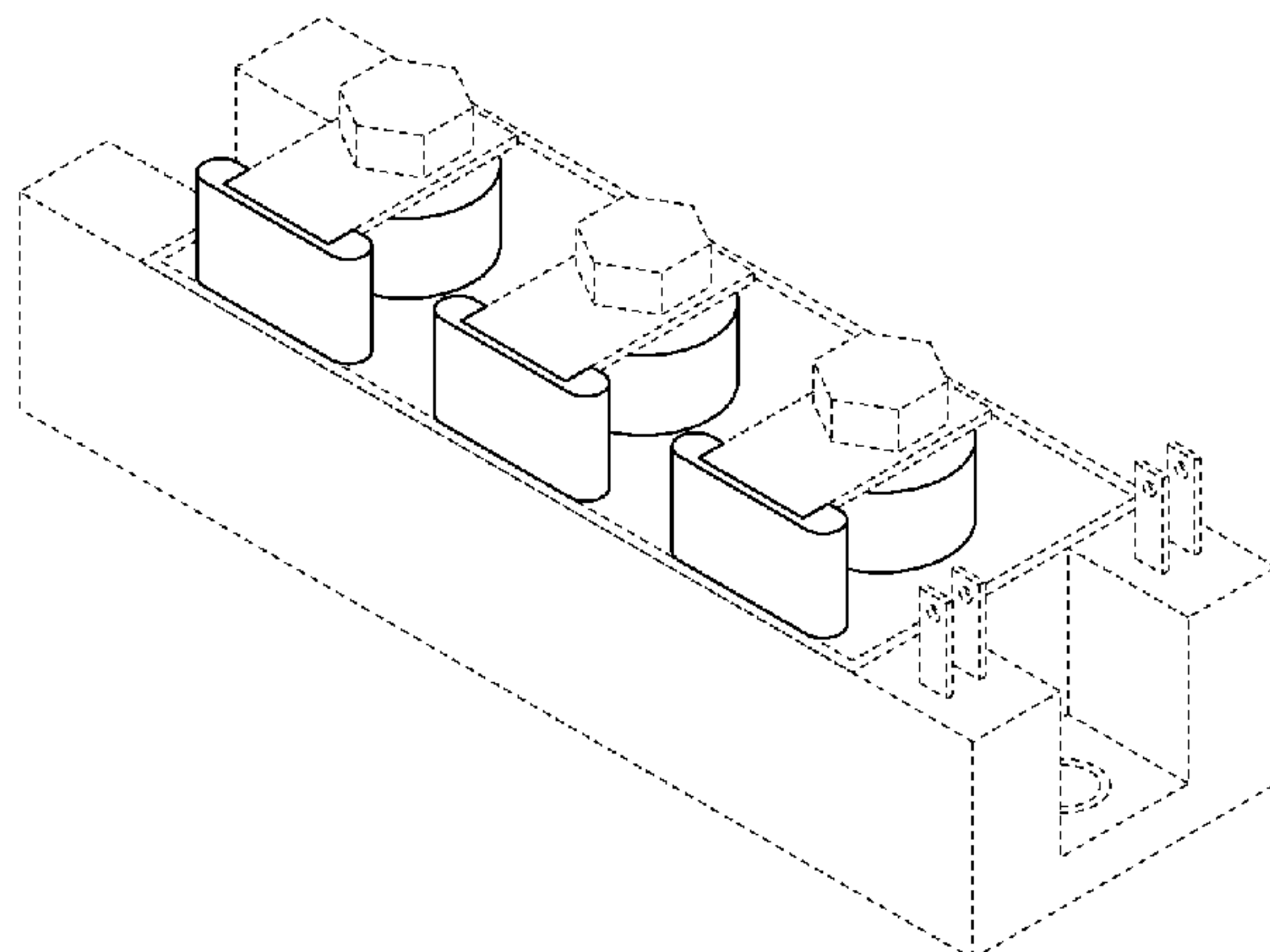
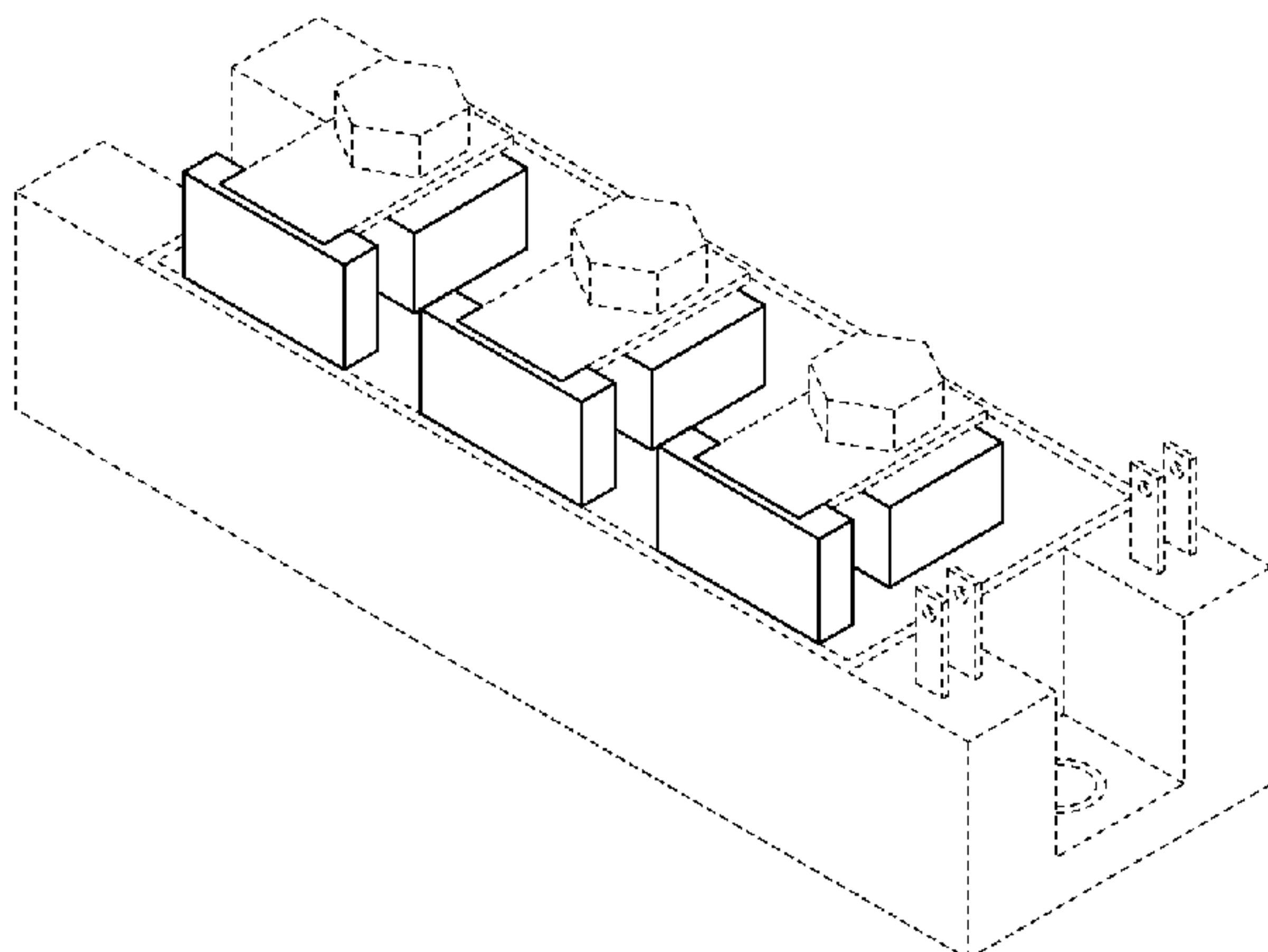
(57) **CLAIM**

The ornamental design for a semiconductor module for power conversion, as shown and described.

DESCRIPTION

FIG. 1 is a front view of a first embodiment of a semiconductor module for power conversion showing my new design; FIG. 2 is a rear view thereof; FIG. 3 is a top view thereof; FIG. 4 is a bottom view thereof; FIG. 5 is a right side view thereof; FIG. 6 is a left side view thereof; FIG. 7 is a front, right, top perspective view thereof; FIG. 8 is a cross sectional view of the semiconductor module for power conversion of FIG. 1 taken along lines 8-8 of FIG. 1; FIG. 9 is a front, right, top perspective view of the semiconductor module for power conversion of FIG. 1 shown in a used condition; FIG. 10 a front view of a second embodiment of a semiconductor module for power conversion showing my new design; FIG. 11 is a rear view thereof; FIG. 12 is a top view thereof; FIG. 13 is a bottom view thereof; FIG. 14 is a right side view thereof; FIG. 15 is a left side view thereof; FIG. 16 is a front, right, top perspective view thereof; FIG. 17 is a cross sectional view of the semiconductor module for power conversion of FIG. 1 taken along lines 17-17 of FIG. 10; and, FIG. 18 is a front, right, top perspective view of the semiconductor module for power conversion of FIG. 10 shown in a used condition. The broken lines shown in the drawings represent portions of the semiconductor module for power conversion that form no part of the claimed design.

1 Claim, 18 Drawing Sheets



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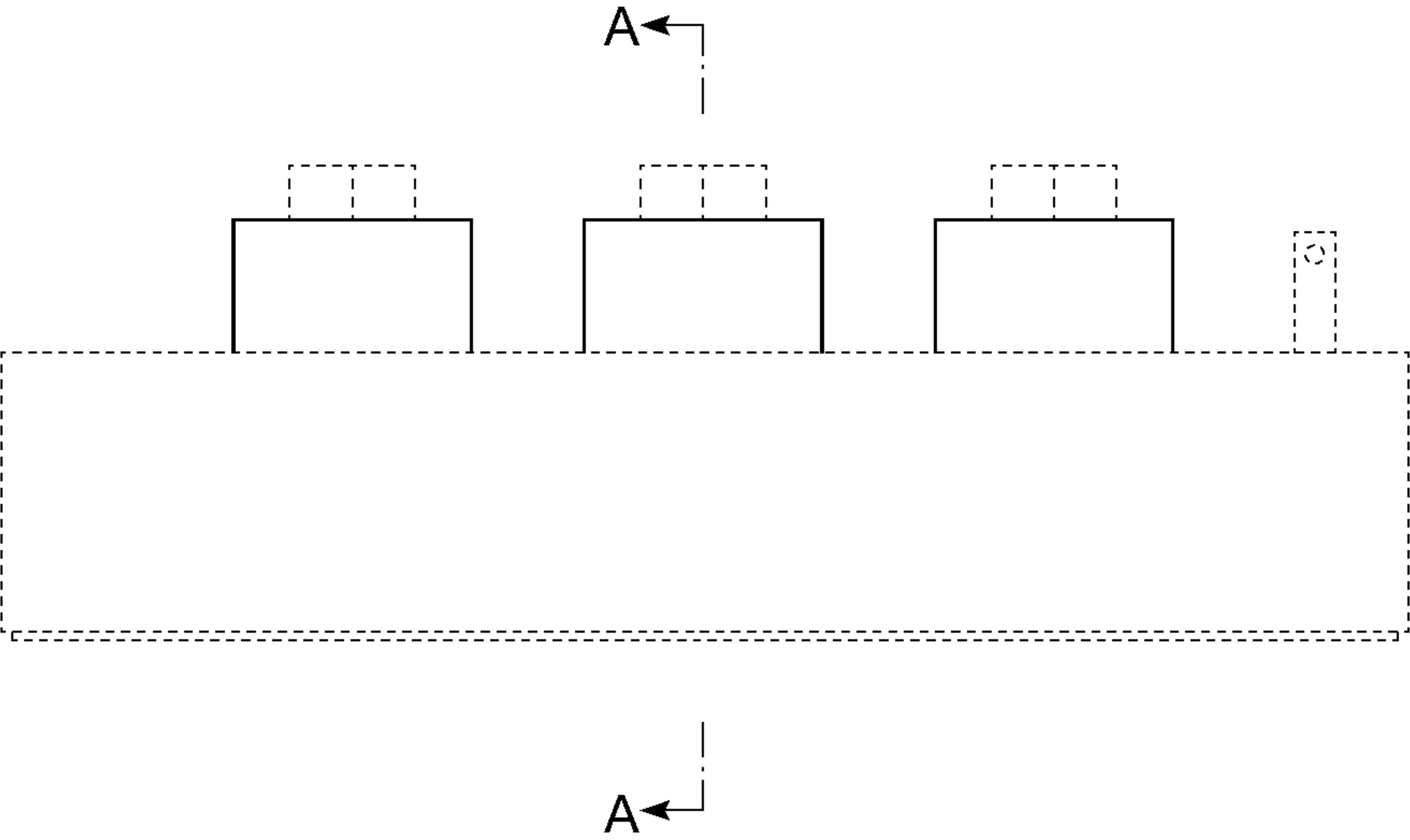


FIG. 1

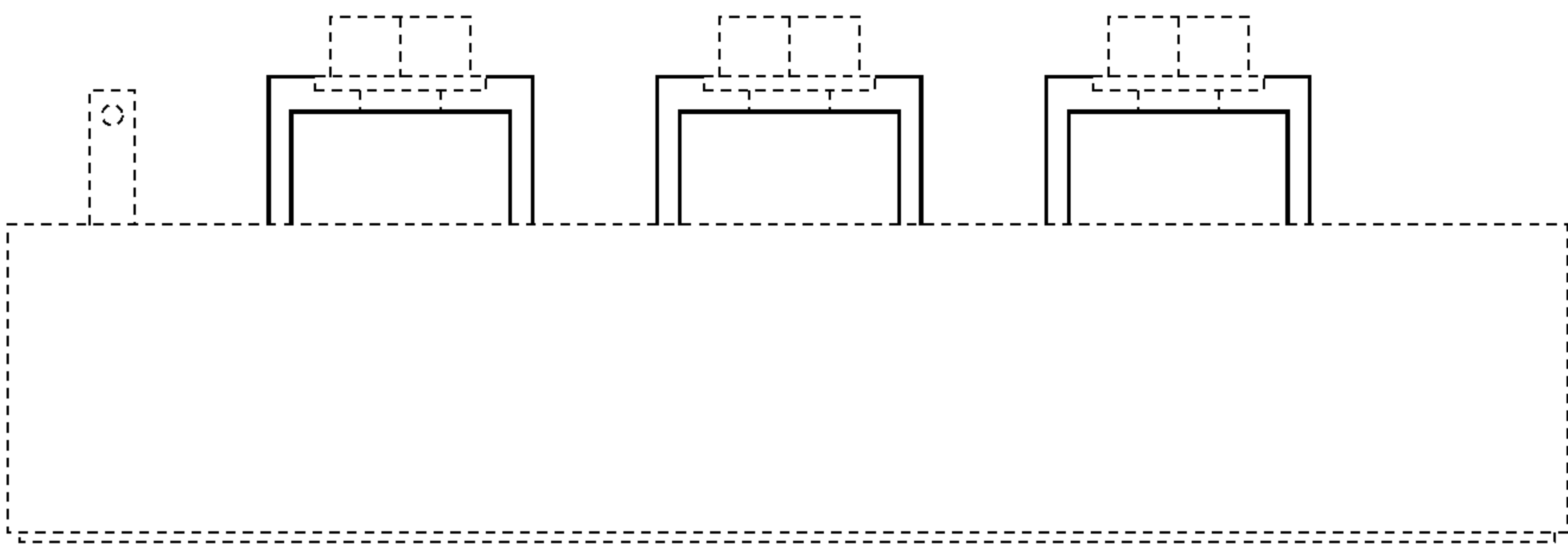


FIG. 2

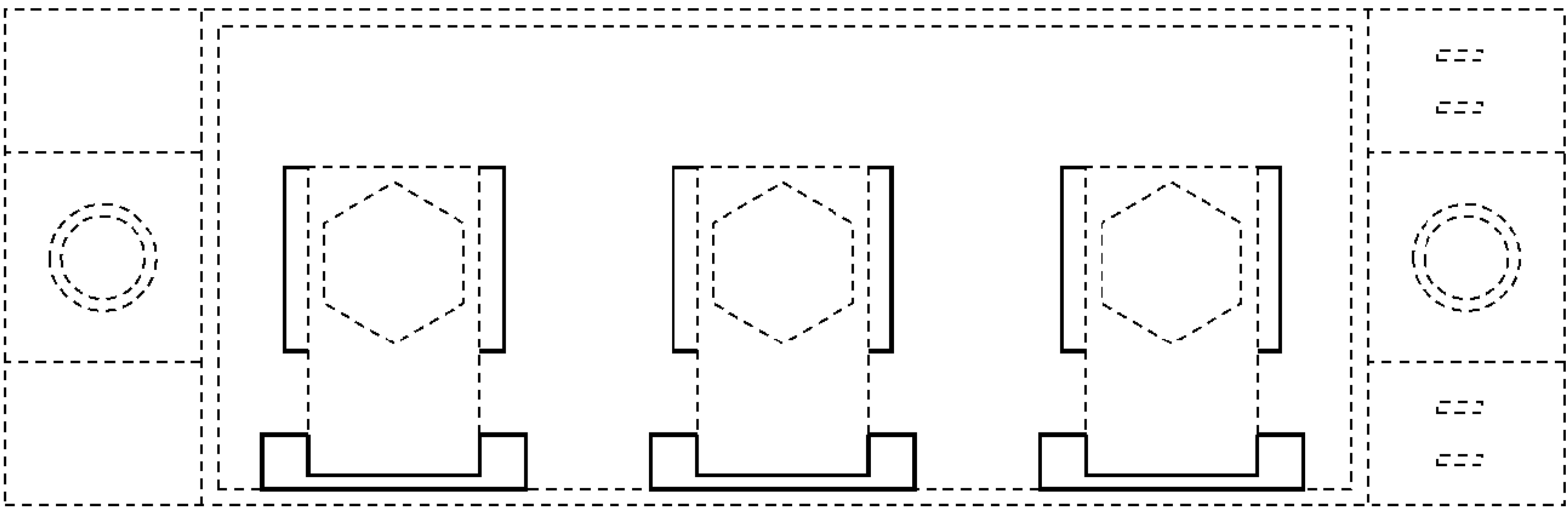


FIG. 3



FIG. 4

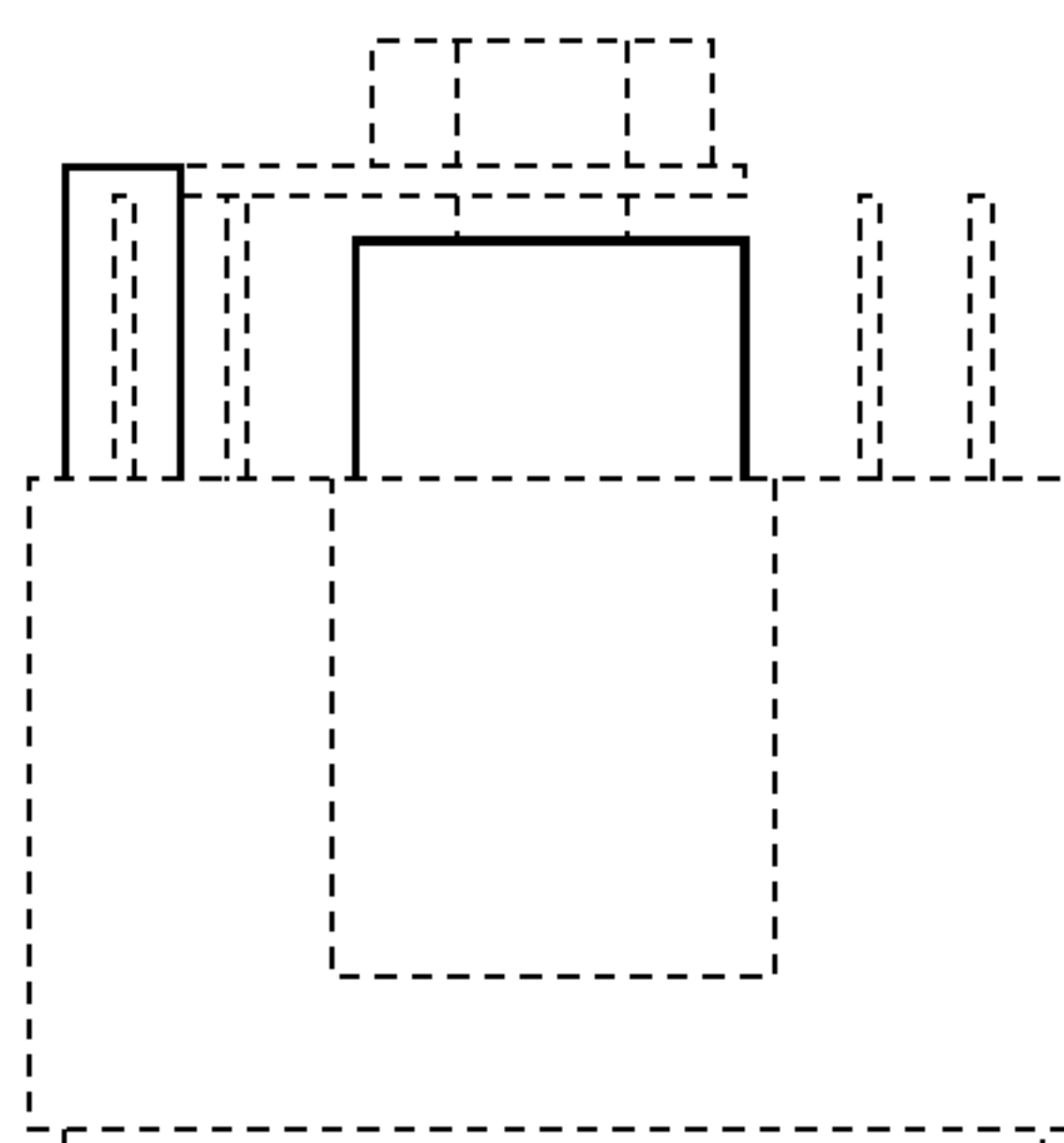


FIG. 5

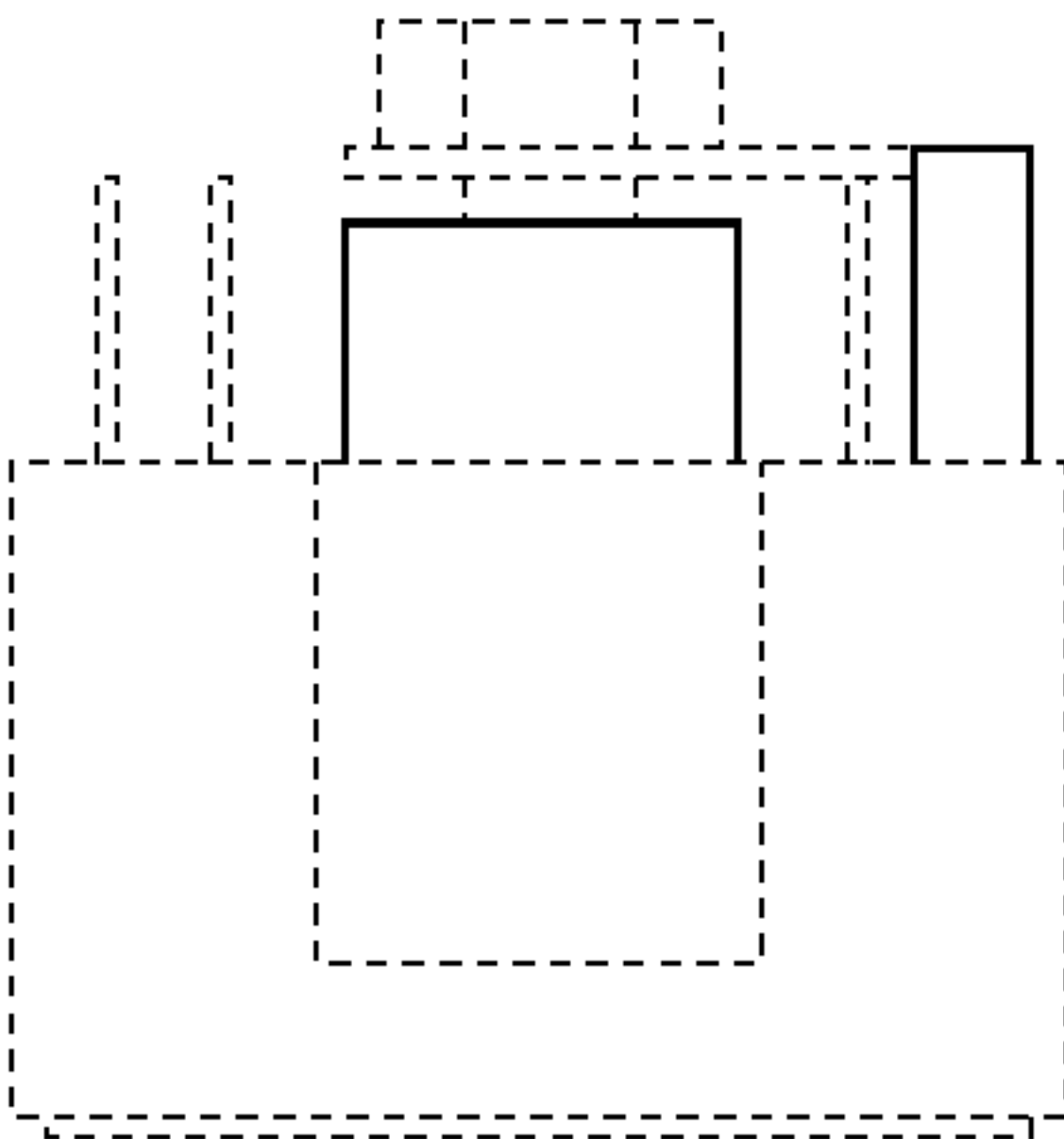


FIG. 6

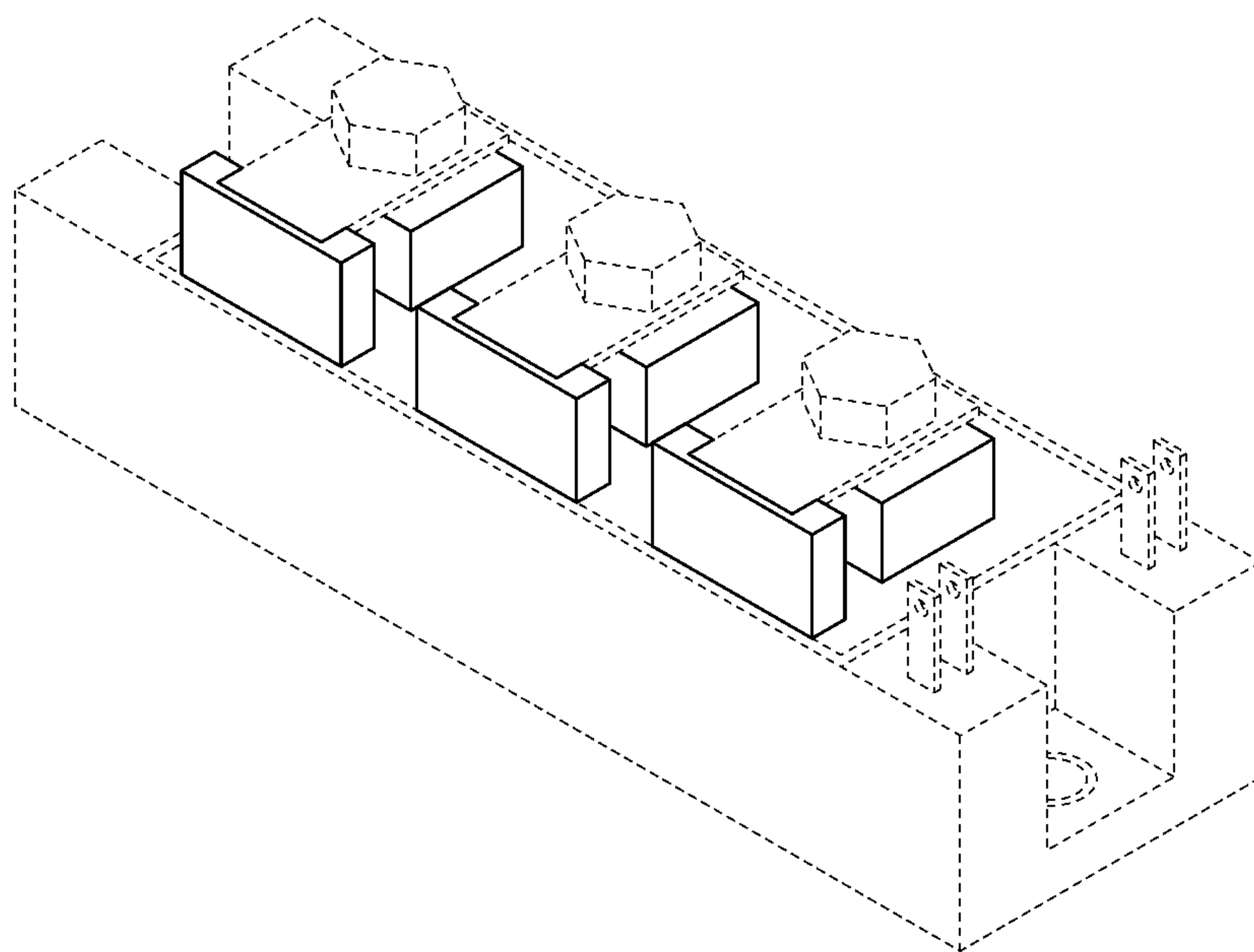


FIG. 7

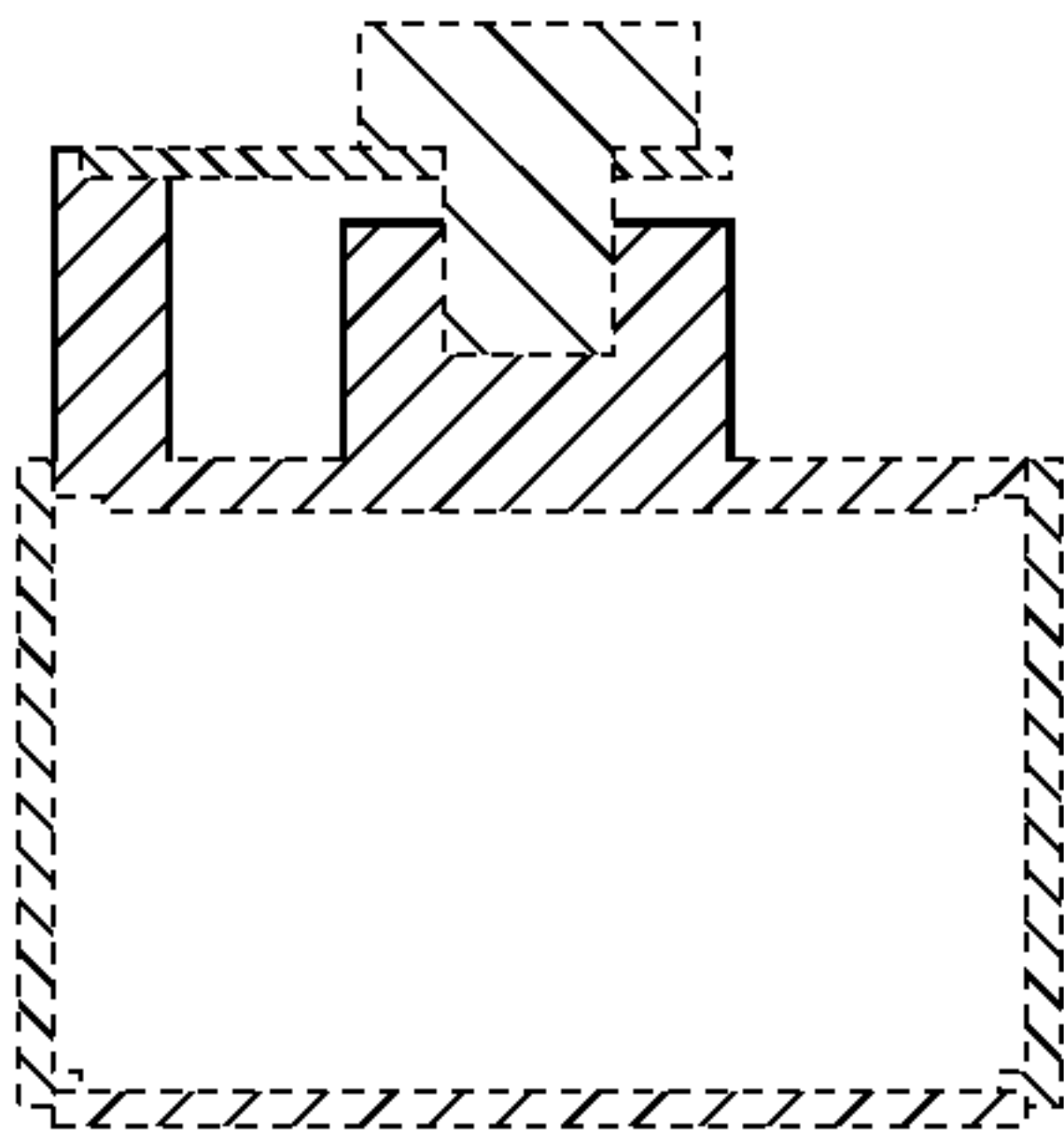


FIG. 8

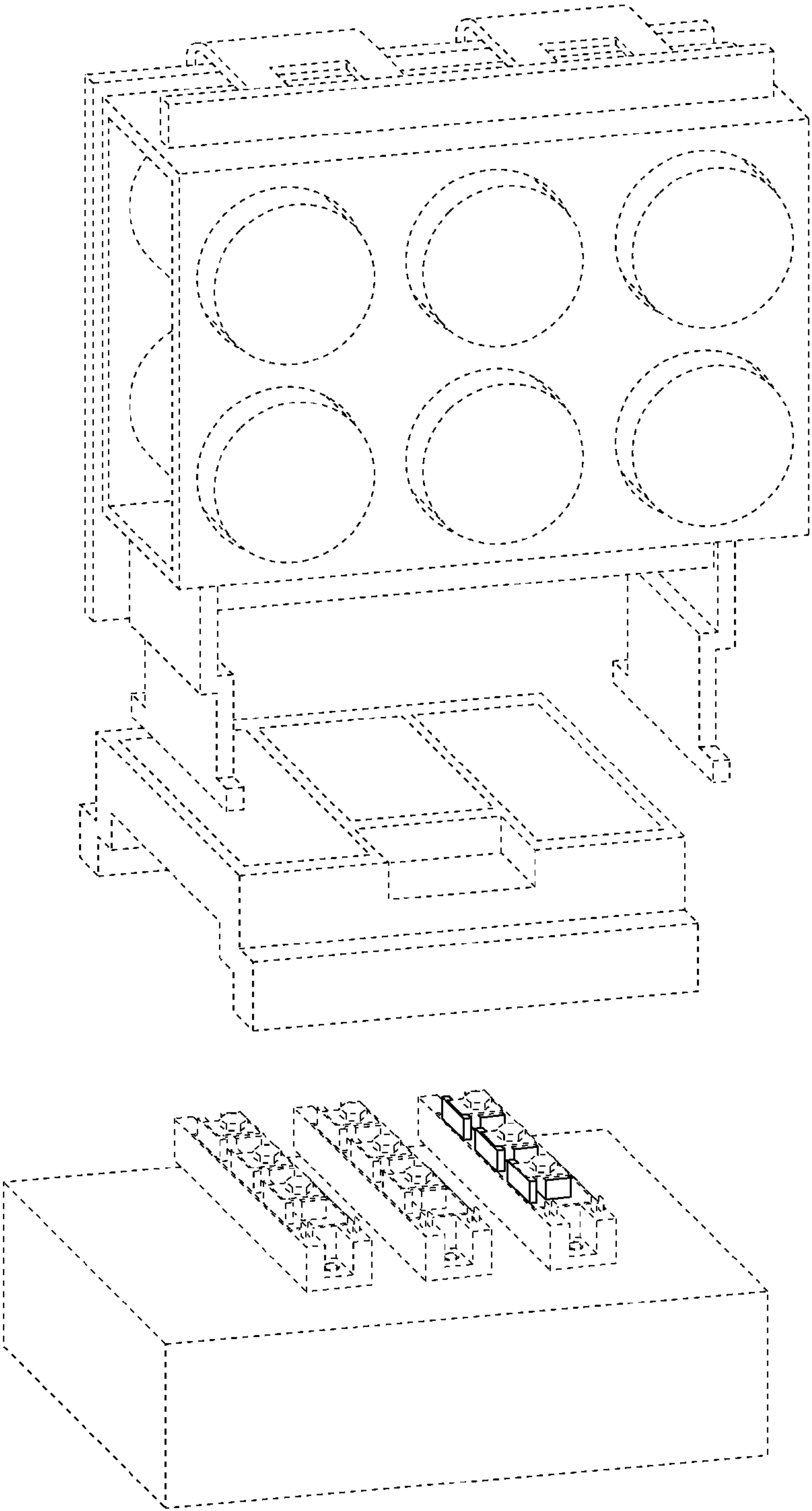


FIG. 9

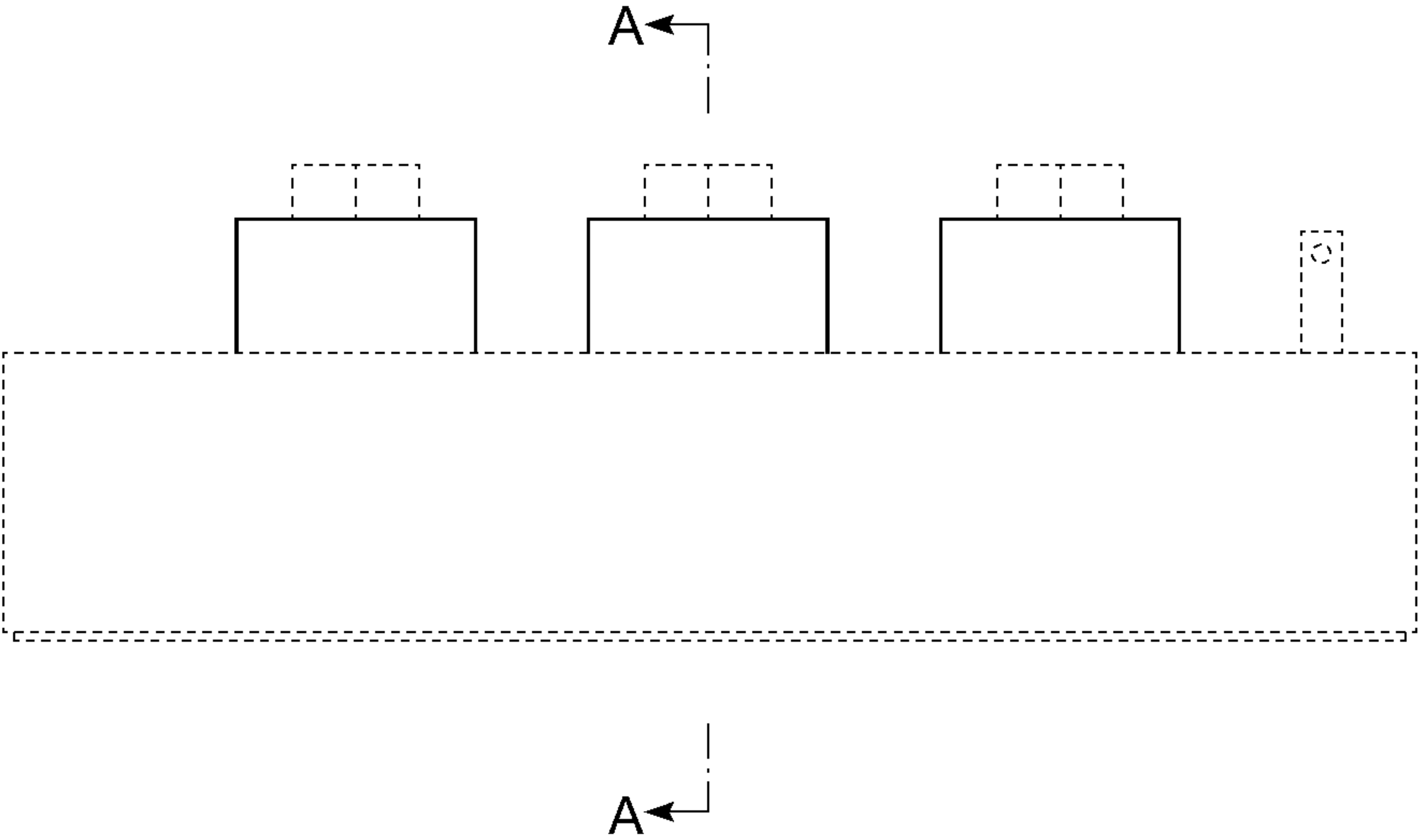


FIG. 10

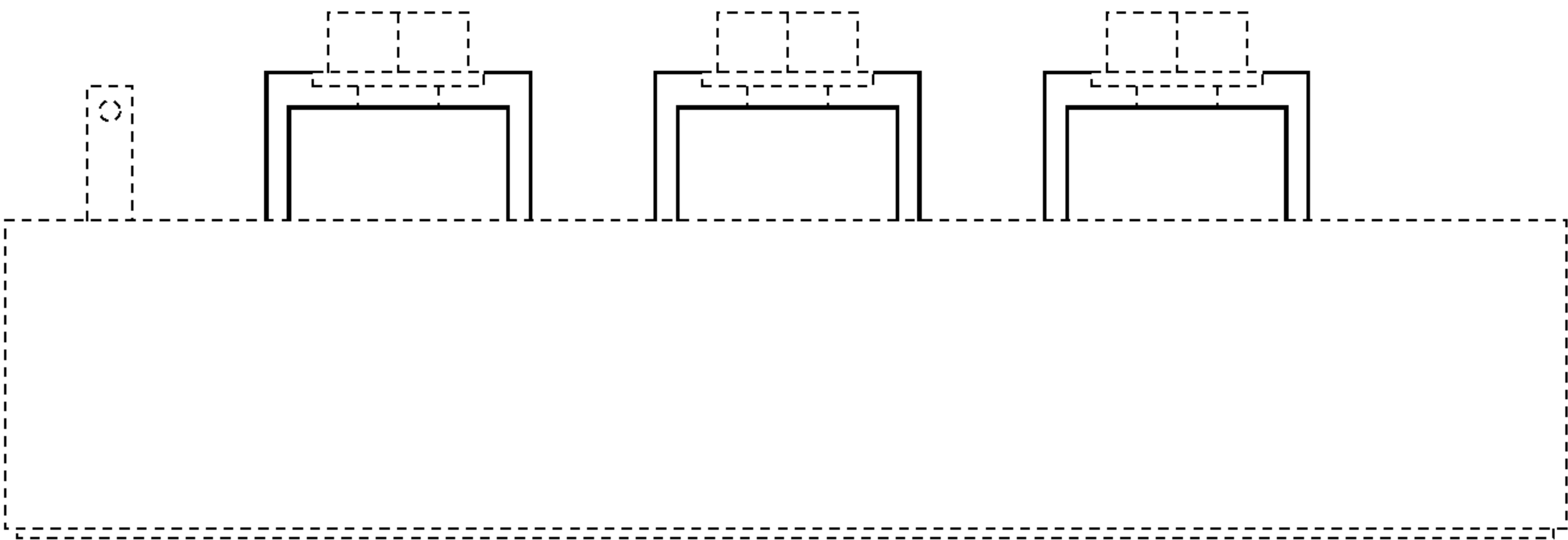


FIG. 11

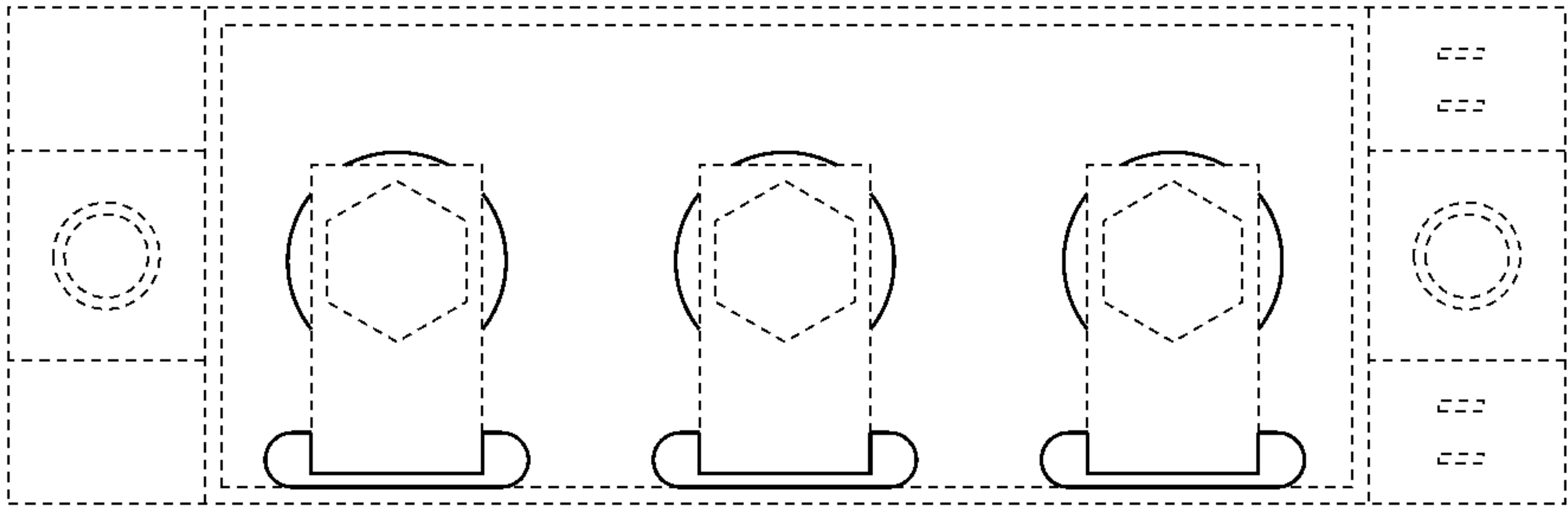


FIG. 12



FIG. 13

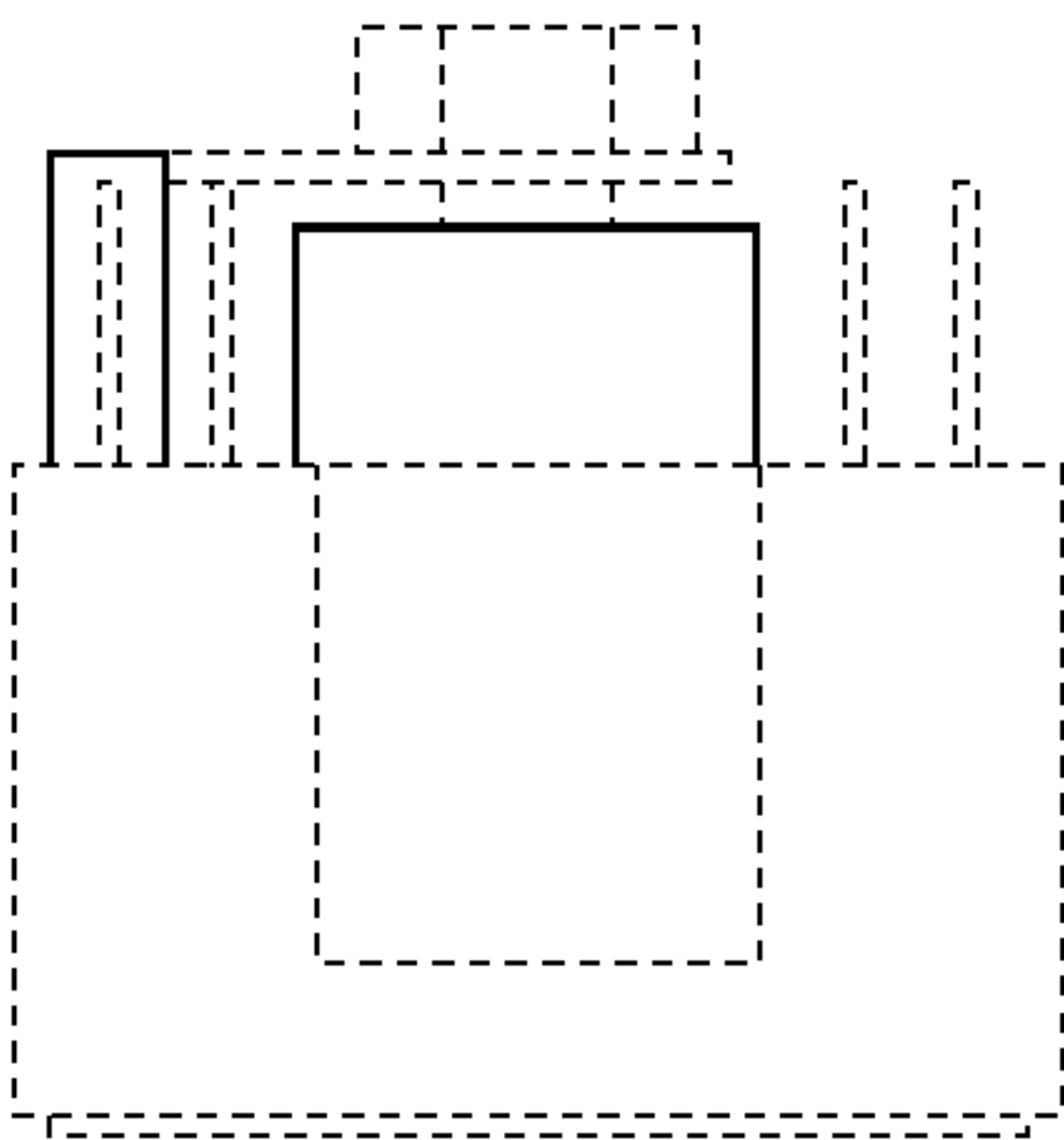


FIG. 14

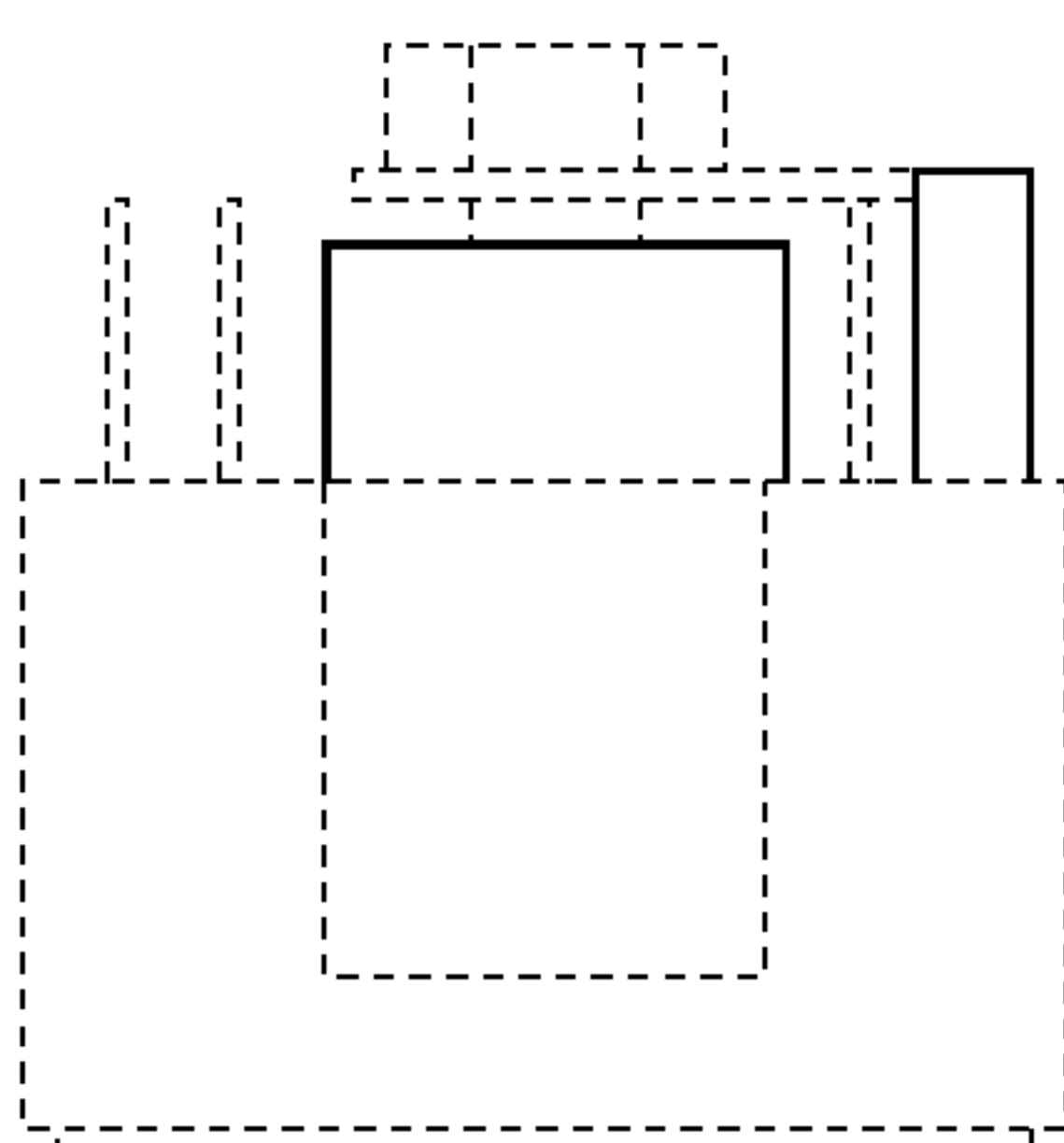


FIG. 15

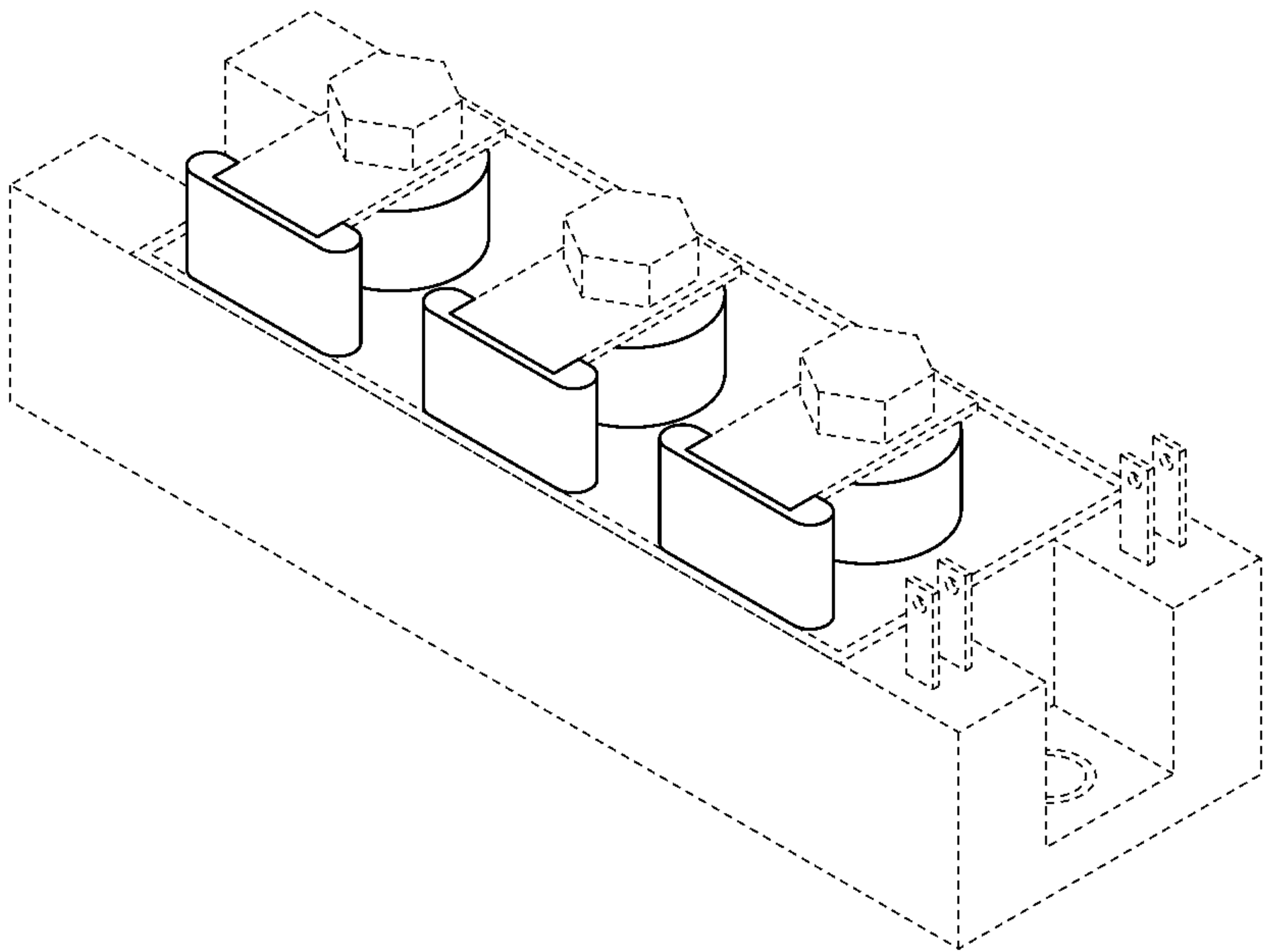


FIG. 16

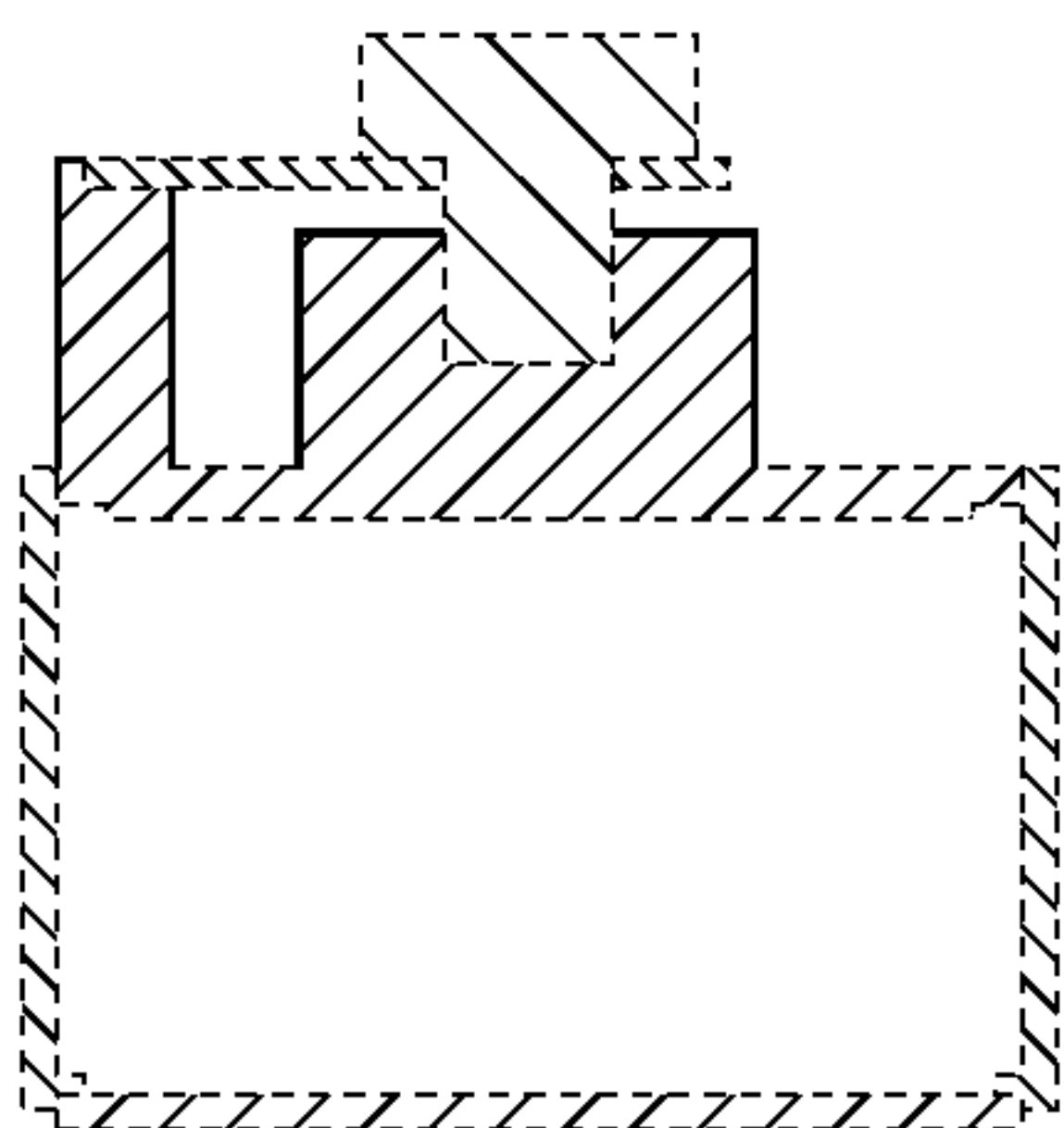


FIG. 17

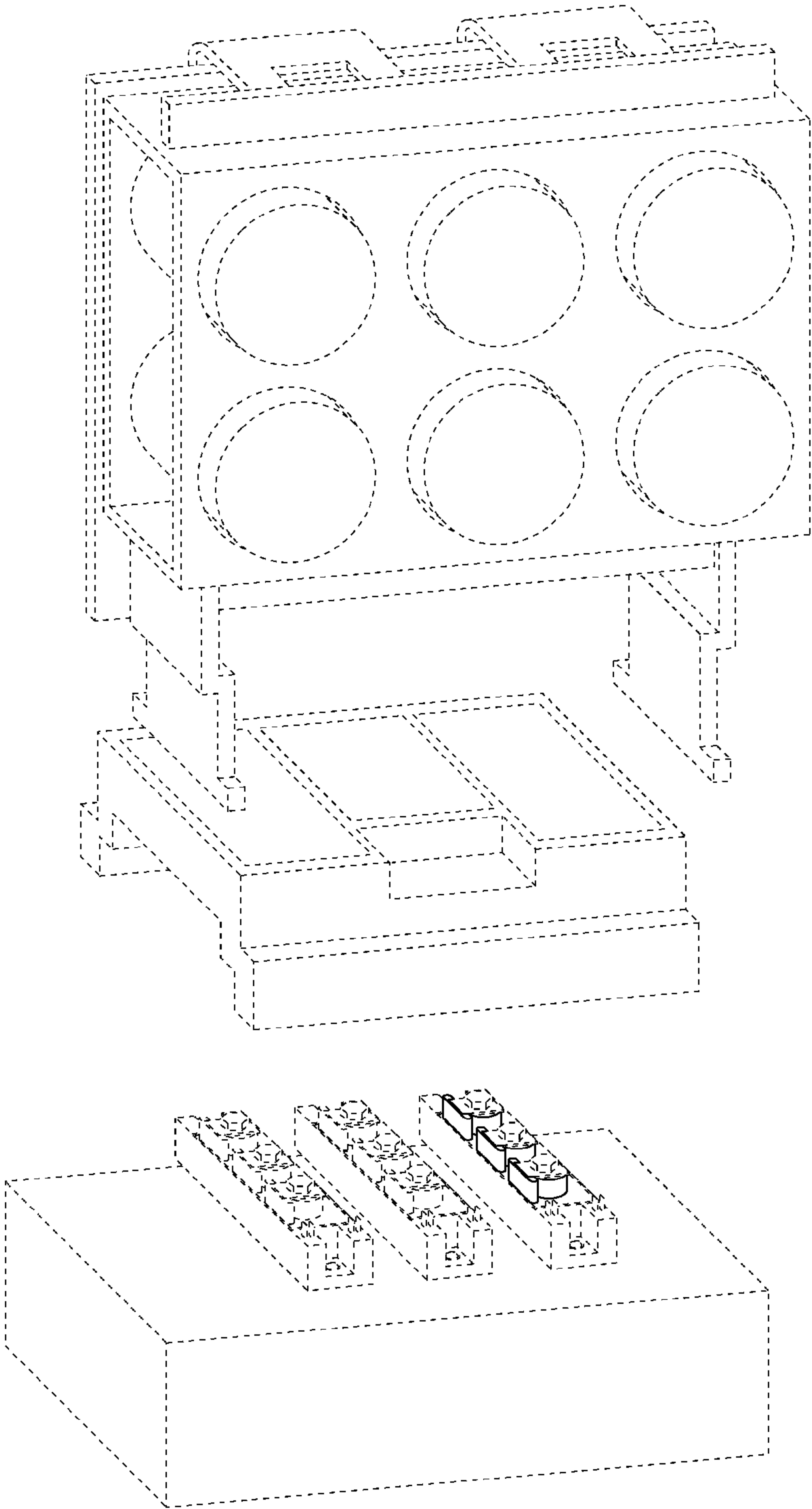


FIG. 18